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09/993,503	11/27/2001	Hoi-Sik Moon	6192.0193.AA	8146
32605 7590 08/17/2007 MACPHERSON KWOK CHEN & HEID LLP 2033 GATEWAY PLACE SUITE 400 SAN JOSE, CA 95110			EXAMINER NGUYEN, HOAN C	
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Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary

Application No.

09/993,503

Applicant(s)

MOON, HOI-SIK

Examiner

HOAN C. NGUYEN

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 30 April 2007.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-14, 17-19 and 21-24 is/are pending in the application.
- 4a) Of the above claim(s) 1-14 is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 15, 17-19 and 21-24 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☐ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date _____
- 4) ☐ Interview Summary (PTO-413)
Paper No(s)/Mail Date. _____
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: _____

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DETAILED ACTION

Claims 1-14 are withdrawn. Claims 16, 20 are cancelled. Claims 15, 17-19 and 21-24 are elected

Response to Amendment

Applicant's arguments with respect to claims 15, 17-19 and 21-24 based on the Response filed on 04/30/2007 have been considered but are in the old ground(s) of rejection. Therefore, this is Final action.

Specification

A substitute specification excluding the claims is required pursuant to 37 CFR 1.125(a) because in the original specification, several paragraphs have been corrected and few paragraphs have been removed. Thus the paragraphs need to be renumbered.

A substitute specification must not contain new matter. The substitute specification must be submitted with markings showing all the changes relative to the immediate prior version of the specification of record. The text of any added subject matter must be shown by underlining the added text. The text of any deleted matter must be shown by strike-through except that double brackets placed before and after the deleted characters may be used to show deletion of five or fewer consecutive characters. The text of any deleted subject matter must be shown by being placed within double brackets if strike-through cannot be easily perceived. An accompanying clean version (without markings) and a statement that the substitute specification

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contains no new matter must also be supplied. Numbering the paragraphs of the specification of record is not considered a change that must be shown.

The amended specification is still not resolved the significant differences between the conventional PCB and the shrinkage PCB; thus the specification objection is repeated.

Specification

The disclosure is objected to under 37 CFR 1.71, as being so incomprehensible as to preclude a reasonable search of the prior art by the examiner. For example, the following items are not understood:

Applicants fail to point out the significant differences between the conventional PCB and the shrinkage PCB. The conventional PCB and the shrinkage PCB both have thermal expansion. The specification discloses:

The reason for this is that the respective thermal reaction properties of the left and the right portions of the printed circuit board 30 are different from each other since the conventional printed circuit board is not symmetric in left and right (paragraph 57).

Thus, so the shrinkage printed circuit board 100 has a length of interest dimension that is shrunk by about 112.5 μm in comparison with that of the conventional printed circuit board 30 (paragraph 59).

What does "a length of interest dimension is shrunk by about 112.5 μm " solve the non-symmetry of the conventional printed circuit board?

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Also, since the amount of thermal expansion of the left portion of the shrinkage printed circuit board 100 is greater than the amount of thermal expansion of the right portion thereof, which, as discussed above, is a result of the asymmetry of the shrinkage printed circuit board 100, the intervals between the respective PCB land groups are set at 19 μm in the portion of the PCB left of the point M and at 13 μm in the portion of the PCB right of the point M (paragraph 60).

What does "the thermal expansion amount of the left portion of the shrinkage printed circuit board 100 is larger than the thermal expansion amount of the right portion of the shrinkage printed circuit board 100" solve the asymmetry of the conventional printed circuit board? Will the shrinkage printed circuit board become more symmetric?

Appropriate correction is required.

The amended specification is also not revolved the interval of first conductive pattern group comparing with the interval of conductive pattern group of a corresponding tape carrier packages; thus the 112 rejection is repeated.

Claim Rejections - 35 USC § 112

The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

Claims 15, 17-19, 21-24 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to

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one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

There is nowhere in a specification discloses:

Claim 15:

- forming a first conductive pattern group on the printed circuit board in accordance with the thermal expansion properties of the printed circuit board such that intervals between ones of the first conductive pattern group are **smaller** than intervals between ones of a corresponding tape carrier packages.

Claim 19:

- a plurality of printed circuit board land groups formed on the substrate, each one of the printed circuit board land groups corresponding one-to-one with one of the tape carrier packages, an interval between the printed circuit board land groups being **smaller** than an interval between tape carrier packages.

Claim 23:

- forming printed circuit board land groups that correspond one-to-one with each of tape carrier packages on a substrate such that an interval between the printed circuit board land groups is **smaller** than an interval between tape carrier packages.

Therefore, these features in claims 15, 19 and 23 consider as New Subject Matter.

In response, applicants admits that the specification describes:

The land groups 120 are composed of a plurality of PCB land groups 120a through 120h, to each of which a corresponding one of a plurality of tape carrier packages (TCPs) is to be attached. As

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illustrated in FIG. 3A, each of the PCB land groups 120a to 120h has a lateral position that is "shrunk", or contracted, by a predetermined dimension in the direction of a point M located on a line perpendicular to the long edge of the PCB (phantom line in FIG. 3A) dividing the substrate 110 into two parts along the length of the substrate 110 relative to the respective lateral positions of corresponding ones of the land groups of the conventional printed circuit board 30 of FIG. 2 (paragraph 54).

In this case, each of the TCPs 200a through 200h is disposed at a predetermined interval (between TCP, not between second conductive pattern group or connection ports) to align in the position, before each PCB land group 120a through 120h respectively corresponding to each of the TCPs 200a through 200h is shrunk (paragraph 64).

Furthermore, the specification also describes:

In the shrinkage printed circuit board 100 having the above-described construction, the input lead 230 of the TCP 200a through 200h is covered with the ACF 130 of the shrinkage printed circuit board 100 by utilizing a movable stage and a fixing member. At that time, the center of each PCB land 120a through 120h is deviated from the center of each TCP 200a through 200h by the shrinkage amount of each PCB land 120a through 120h, thereby forming a pre-compression state (paragraph 65).

Also, as described below, the total amount of thermal expansion of each tape carrier package is assumed to have a constant value ($= 2\beta$) that is independent of the expansion of either the shrinkage printed circuit board 100 or the conventional printed circuit board 30 during the thermo-compression bonding process (paragraph 73).

As shown in Table 3, the average value of each thermal expansion amount of each TCP is about 37.3 pm (the standard deviation is 2) when the shrinkage printed circuit board 100 is thermo-compressed. Also, as shown in Table 5, the average value of each thermal expansion amount of each TCP is about 42.17pm (the standard deviation is 0.988) when the conventional printed circuit board is thermo-compressed (paragraph 74).

When the thermo-compression process is performed on the first TCP 200a and the first PCB land group 120a, the left end of the first PCB land group 120a moves toward a first dotted line 420 due to the thermal expansion of the substrate 110 and the left end of the first TCP 200a also moves toward the second dotted line 520 for the same reason. Hence, after the thermo-compression bonding process, the first TCP 200a is expanded by an interval ($- [3]$) between the second real line 510 and the second dotted line 520. Also, the first PCB land group 120a expands by an interval ($P\sim$) between the first real line 410 and the first dotted line 420. Then, the measured misalignment value becomes the interval ($A1$) from the second dotted line 520 to the first dotted line 420 (paragraph 79).

When the thermo-compression process is performed on the eighth TCP 200h and the eighth PCB land group 120h, the left end of the eighth PCB land group 120h moves toward the first dotted line 620 due to the thermal expansion of the substrate 110, and the left end of the eighth TCP 200h also moves toward the second dotted line 720 due to the thermal expansion of the

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substrate. Hence, after the thermo-compression bonding process, the eighth TCP 200h is expanded by an interval (- 13) between the second real line 710 and the second dotted line 720. The eighth PCB land group 120h also expands by an interval (P8) between the first real line 610 and the first dotted line 620. Also, the measured misalignment value becomes the interval (A8) from the second dotted line 720 to the first dotted line 620 (paragraph 82).

FIGS. 7A and 7B are plane views showing the relative position between the respective PCB land groups and the corresponding TCPs of Sample 1 in Table 2 after the thermo-compression bonding process. FIG. 7A is a plane view illustrating the alignment state between the first PCB land group and the first TCP 200a and FIG. 7B is a plane view showing the alignment state between the eighth PCB land group 120h and the eighth TCP 200h (paragraph 96).

In Table 2, the amount of misalignment is measured on the basis of each edge of TCPs 200a through 200h for convenience of measurement. However, the precise amount of misalignment should be measured on the basis of each PCB land group 120a through 120h and the center of each corresponding lead group of TCPs 200a through 200h because misalignment here means an irregularity among the respective conductive patterns (*i.e.*, a misalignment between respective PCB land groups 120 and corresponding TCP 200 lead groups) that are used for exchanging the electrical signals between the printed circuit board 100 and the tape carrier packages 200 (paragraph 121).

Examiner looks over the specification but this invention illustrates the differences of the thermal expansions of PCB and TCP, **NOT** "interval between the printed circuit board land groups" or "interval between tape carrier packages land groups" cited in claims 15, 19 and 23.

In conclusion, claims 15, 19 and 23 are rejected due to having new subject matter, therefore, claims 17-18, 21-22 and 24 are rejected since they depend on the infinite claims.

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In the event that the applicants argue that the above 112, 1st paragraph rejection is inappropriate because the invention is inherent in the disclosure, the following rejection in view of admitted prior art are appropriate:

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 15, 17-19, 21 and 22-23 are rejected under 35 U.S.C. 102(b) as being anticipated by the conventional art admitted by applicants.

The conventional arts (Tables 1, 4-5, 8-9, 11 and Figs. 1, 2 4, 8, 10-11) disclose a method for manufacturing a bonded adherent member and printed circuit board comprising

Claim 15:

- forming a first conductive pattern group on the printed circuit board in accordance with the thermal expansion properties of the printed circuit board such that intervals between ones of the first conductive pattern group are smaller than intervals between ones of a corresponding tape carrier packages;
- thermocompression bonding the adherent member and the printed circuit board;

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- during the thermocompression bonding, allowing the printed circuit board to expand such that the first conductive pattern group is substantially aligned with second conductive pattern group on tape carrier packages.

Wherein

Claim 17:

- inherently before said forming, measuring the thermal expansion properties of the printed circuit board.

Claim 18:

- the intervals between ones of the first conductive pattern group are asymmetric when the printed circuit board is asymmetric.

The conventional arts (Tables 1, 4-5, 8-9, 11 and Figs. 1, 2 4, 8, 10-11) disclose a printed circuit board that is to be electrically connected to an external device through a plurality of connection ports spaced apart part from each other, the printed circuit board comprising:

Claim 19:

- a substrate; and
- a plurality of printed circuit board land groups formed on the substrate, each one of the printed circuit board land groups corresponding one-to-one with one of the tape carrier packages, an interval between the printed circuit board land groups being smaller than an interval between the tape carrier packages (to able to electrical connection each one of the printed circuit board land groups must corresponds one-to-one with one of the tape carrier packages).

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Claim 21:

- the interval between the printed circuit board land groups becomes substantially same as the interval of the one of the printed circuit board land groups corresponding one-to-one with one of the tape carrier packages by thermal expansion when the printed circuit board undergoes a thermo-compression bonding process.

Claim 22:

- the intervals between ones of the first conductive pattern group are asymmetric when the printed circuit board is asymmetric.

In regard to claim 23, The conventional arts (Tables 1, 4-5, 8-9, 11 and Figs. 1, 2 4, 8, 10-11) disclose a method of manufacturing a printed circuit board that is to be electrically connected to an external device through a plurality of connection ports spaced apart from each other, comprising:

- forming printed circuit board land groups that correspond one-to-one with each of the one of the printed circuit board land groups corresponding one-to-one with one of the tape carrier packages of the external device on a substrate such that an interval between the printed circuit board land groups is smaller than an interval between the one of the printed circuit board land groups corresponding one-to-one with one of the tape carrier packages.

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Conclusion

1. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to **HOAN C. NGUYEN** whose telephone number is (571) 272-2296. The examiner can normally be reached on **MONDAY-THURSDAY:8:00AM-4:30PM**.


If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, David Nelms can be reached on (571) 272-1787. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

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Art Unit 2871

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